

## **Optimal Corporation Welcomes Jamie Metcalfe as Vice President of Business Development**

### *Accomplished EDA Professional to drive System-in-Package (SiP) Initiatives*

SAN JOSE, California – April 27, 2006 – Optimal Corporation, a leading provider of 3D power and signal integrity analysis for IC Package, System-in-Package (SiP) and PCB design, today announced that it has expanded its executive management team by appointing former Cadence Design Systems (NASDAQ:CDNS) executive, Jamie Metcalfe, as its new Vice President of Business Development. Metcalfe will work with Optimal CEO, Dave DeMaria, to develop and execute the company's initiatives in the area of System-in-Package (SiP).

Metcalfe joins Optimal as a successful and accomplished executive with over 20 years of experience in the EDA industry, with the last ten years being at Cadence Design Systems. During his Cadence tenure, Metcalfe held positions including Vice President of Marketing for Systems-in-Package and PCB systems design where he was responsible for product strategy, developing strategic relationships with customers and partners, and marketing activities. Prior to Cadence, Jamie spent ten years at Mentor Graphics, most recently as the European field marketing manager for the company's Systems Design product lines. Jamie began his career with Racal-Redac (now part of Zuken) where he worked as a software engineer and team leader.

DeMaria said, "Jamie comes to Optimal at an exciting time. As the leader for 3D signal integrity and power analysis in the IC Packaging market, System-in-Package represents a key growth area for our customers and our company. Jamie helped establish Cadence as the definitive leader in the IC Packaging market and most recently has been driving their SiP initiative. His knowledge of the technology trends and customer needs will be extremely valuable to Optimal as we expand into the SiP market."

Metcalfe stated, "I'm excited to become a part of the Optimal team at a time when signal and power integrity are becoming such critical issues for the electronics industry, and while the company is in a phase of rapid growth. While at Cadence, I developed the strategic relationship with Optimal, so I am very familiar with their strong technology and their innovative team. Having dedicated the last two years of my career to the SiP market opportunity, I believe that Optimal has the right strategy, technology, and partnerships to become the leader in analysis for the SiP market and I look forward to helping Optimal achieve that objective."

### **About Optimal Corporation**

Optimal Corporation, founded in 1995, is the leader in 3D power and signal integrity analysis for IC Package, System-in-Package (SiP) and PCB design. Our innovative solutions enable design teams to concurrently analyze and optimize the IC together with the Package and the Packaged IC on the PCB.

By providing the highest performance, best ease-of-use and pinpoint accuracy, our solutions allow engineers to create designs optimized for power and signal integrity in the shortest possible time. Through seamless integration with all of the major CAD design flows, Optimal solutions help customers achieve the shortest and most efficient overall design cycle time.

Optimal's technology is embedded in the Cadence Allegro flow and endorsed in the TSMC Reference Flow. Optimal is a TSMC Technology Alliance Partner and a member of the Cadence Connections Emerging Solutions Program.

Optimal has over 50 customers around the globe, including many of the world's leading semiconductor, IC packaging and systems companies. For more information visit [www.optimalcorp.com](http://www.optimalcorp.com)

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